

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Group Art Unit: 2826 Examiner: Fazli Erdem

In re PATENT APPLICATION of

Applicants: Takahiro OKA et al.

Appl. No.: 09/912,064

Filed : July 25, 2001

For : SEMICONDUCTOR CHIP PACKAGE

Atty. Dkt.: TAI 129

AMENDMENT

June 20, 2002

Box Non-Fee Amendment

Commissioner of Patents Washington, D.C. 20231

Sir:

In response to the Examiner's Action dated March 20, 2002, please amend this application as follows:

IN THE CLAIMS

Please cancel claim 2 and amend claims 1 and 3-12 without prejudice or disclaimer,

as follows:

1. (Amended) A semiconductor chip package comprising:

Subi

A